

General Description

The 50N06B combines advanced trench MOSFET technology with a low resistance package to provide extremely low RDS(ON).

This device is ideal for boost converters and synchronous rectifiers for consumer, telecom, industrial power supplies and LED backlighting.

Features

- 50A,60V.RDS(ON)=0.013Ω@VGS=10V
- N-channel-Enhancement mode
- Low Threshold Drive
- 100% Avalanche Tested
- Green Device Available

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	±20	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current ¹	50	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current ¹	35	A
I_{DM}	Pulsed Drain Current ²	150	A
EAS	Single Pulse Avalanche Energy ³	85	mJ
I_{AS}	Avalanche Current	35	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation	75	W
T_{STG}	Storage Temperature Range	-55 to 175	°C
T_J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	50	°C/W
$R_{\theta JC}$	Thermal Resistance Junction -Case	---	2.1	°C/W

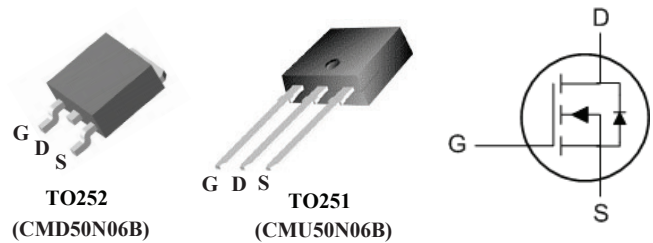
Product Summary

BVDSS	RDSON	ID
60V	13mΩ	50A

Applications

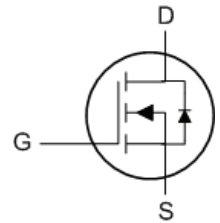
- DC-DC & DC-AC Converters
- Motor Control, Audio Amplifiers
- High Current, High Speed Switching
- Primary Switch for 12V and 24V system

TO252 / TO251 Pin Configuration



TO252
(CMD50N06B)

TO251
(CMU50N06B)



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	---	---	V
ΔBV _{DSS} /ΔT _J	BVDSS Temperature Coefficient	Reference to 25 °C, I _D =250μA	---	0.065	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =50A	---	11	13	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250μA	2	---	4	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =60V, V _{GS} =0V, T _J =25°C	---	---	1	μA
		V _{DS} =60V, V _{GS} =0V, T _J =125°C	---	---	100	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =20A	---	32	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	1.2	---	Ω
Q _g	Total Gate Charge	V _{DS} =30V, V _{GS} =10V, I _D =50A	---	35	---	nC
Q _{gs}	Gate-Source Charge		---	10	---	
Q _{gd}	Gate-Drain Charge		---	8	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =30V, V _G =10V, R _G =9.6Ω I _D =50A	---	12	---	ns
T _r	Rise Time		---	86	---	
T _{d(off)}	Turn-Off Delay Time		---	35	---	
T _f	Fall Time		---	26	---	
C _{iss}	Input Capacitance	V _{DS} =30V, V _{GS} =0V, f=1MHz	---	5600	---	pF
C _{oss}	Output Capacitance		---	540	---	
C _{rss}	Reverse Transfer Capacitance		---	110	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ¹	V _G =V _D =0V, Force Current	---	---	50	A
I _{SM}	Pulsed Source Current ²		---	---	150	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =50A, T _J =25°C	---	---	1.25	V

Note :

- 1.The data tested by surface mounted on a 1 inch²FR-4 board with 20Z copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=36A